

Power Bridge Rectifiers

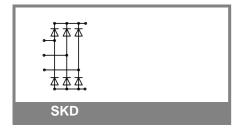
SKD 51

Features

- Glass passivated silicon chips
- Fast-on terminals for pcb solder or plug on connections
- Sturdy insulated metal base plate
- Low thermal impedance through use of direct copper bonded aluminum substrate
- Blocking voltage up to 1800V
- High surge currents
- UL recognized, file no. E63 532

Typical Applications

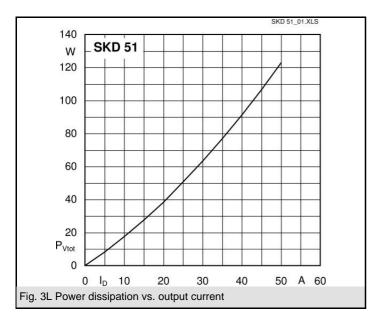
- Three phase rectifier for power supplies
- Input rectifier for variable frequency drives
- Rectifier for DC motor field supplies
- Battery charger rectifiers
- Recommended snubber network: RC: 0.1 μ F, 50 Ω (P $_{R}$ = 1 W)
- For solder connection. Permissible current for plug connection see DIN IEC 760E and DIN 46249 part 1
- 2) Freely suspended or mounted on an insulator
- 3) Mounted on a painted metal sheet of min. 250 x 250 x 1 mm

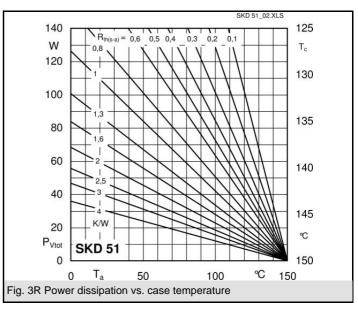


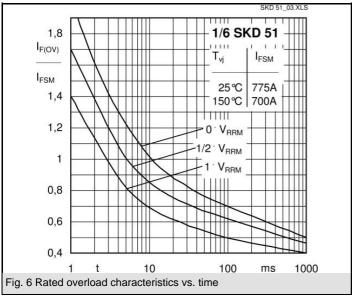
V_{RSM}	V_{RRM}, V_{DRM}	I _D = 50 ¹⁾ A (full conduction)
V	V	(T _c = 127 °C)
500	400	SKD 51/04
900	800	SKD 51/08
1300	1200	SKD 51/12
1500	1400	SKD 51/14
1700	1600	SKD 51/16
1900	1800	SKD 51/18

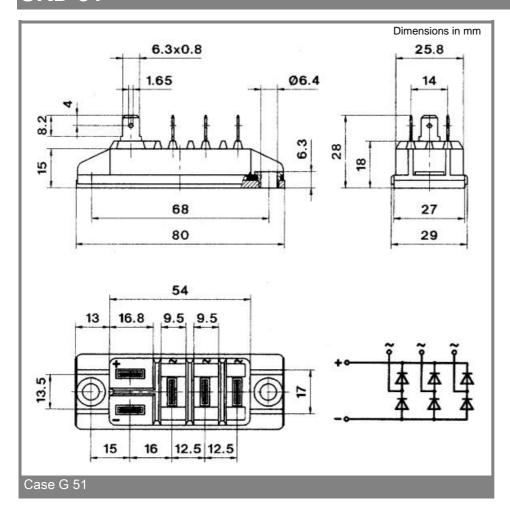
Symbol	Conditions	Values	Units
I _D	T _c = 127 °C	50	Α
	T _a = 45 °C; isolated ²⁾	7	Α
	T _a = 45 °C; chassis ³⁾	18	Α
	T _a = 45 °C; R4A/120	27	Α
	T _a = 45 °C; P5A/100	31	Α
I _{FSM}	T _{vj} = 25 °C; 10 ms	775	Α
	T_{vj} = 150 °C; 10 ms	700	Α
i²t	$T_{vj} = 25 ^{\circ}\text{C}; 8,3 \dots 10 \text{ms}$	3000	A²s
	T _{vj} = 150 °C; 8,3 10 ms	2450	A²s
V _F	T _{vi} = 25 °C; I _F = 75 A	max. 1,45	V
V _(TO)	T _{vi} = 150 °C	max. 0,8	V
r _T	T _{vi} = 150 °C	max. 8,5	$\text{m}\Omega$
I _{RD}	$T_{vj} = 25 \text{ °C}; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$	max. 0,2	mA
	$T_{vj} = 150 ^{\circ}\text{C}; V_{RD} = V_{RRM}$	4	mA
t _{rr}	$T_{vj} = 25 \text{ °C}; I_F = I_R = 1A$	5	μs
R _{th(j-c)}	per diode	1,1	K/W
	total	0,183	K/W
R _{th(c-s)}	total	0,1	K/W
R _{th(j-a)}	isolated ²⁾ (chassis ³⁾)	9 (3,15)	K/W
T _{vi}		- 40 + 150	°C
T _{stg}		- 40 + 125	°C
V _{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 (3000)	V
M _s	to heatsink	4,5 ± 15 %	Nm
M_t			
m		97	g
Case		G 51	

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